PMEG3005EB; PMEG3005EL

0.5 A very low V_F MEGA Schottky barrier rectifiers

Rev. 01 — 29 November 2006 Product data sheet

1. Product profile

1.1 General description

Planar Maximum Efficiency General Application (MEGA) Schottky barrier rectifiers with an integrated guard ring for stress protection, encapsulated in ultra small Surface-Mounted Device (SMD) plastic packages.

Table 1. Product overview

Type number	Package		Configuration
	NXP	JEITA	
PMEG3005EB	SOD523	SC-79	single
PMEG3005EL	SOD882	-	single

1.2 Features

- Forward current: $I_F \leq 0.5$ A
- Reverse voltage: $V_R \leq 30$ V
- Very low forward voltage
- Ultra small SMD plastic packages

1.3 Applications

- Low voltage rectification
- High efficiency DC-to-DC conversion
- Switch mode power supply
- Reverse polarity protection
- Low power consumption applications

1.4 Quick reference data

Table 2. Quick reference data

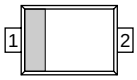
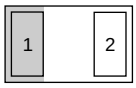
Symbol	Parameter	Conditions		Min	Typ	Max	Unit
I_F	forward current	$T_{sp} \leq 55$ °C		-	-	0.5	A
V_R	reverse voltage			-	-	30	V
V_F	forward voltage	$I_F = 500$ mA	[1]	-	430	500	mV

[1] Pulse test: $t_p \leq 300$ µs; $\delta \leq 0.02$.

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2. Pinning information

Table 3. Pinning

Pin	Description		Simplified outline	Symbol
SOD523				
1	cathode	[1]		 sym001
2	anode			
SOD882				
1	cathode	[1]	 Transparent top view	 sym001
2	anode			

[1] The marking bar indicates the cathode.

3. Ordering information

Table 4. Ordering information

Type number	Package		
	Name	Description	Version
PMEG3005EB	SC-79	plastic surface-mounted package; 2 leads	SOD523
PMEG3005EL	-	leadless ultra small plastic package; 2 terminals; body 1.0 × 0.6 × 0.5 mm	SOD882

4. Marking

Table 5. Marking codes

Type number	Marking code
PMEG3005EB	KB
PMEG3005EL	AM

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5. Limiting values

Table 6. Limiting values

In accordance with the Absolute Maximum Rating System (IEC 60134).

Symbol	Parameter	Conditions		Min	Max	Unit
V_R	reverse voltage			-	30	V
I_F	forward current	$T_{sp} \leq 55$ °C		-	0.5	A
I_{FRM}	repetitive peak forward current	$t_p \leq 1$ ms; $\delta \leq 0.25$		-	1	A
I_{FSM}	non-repetitive peak forward current	square wave; $t_p = 8$ ms		-	3	A
P_{tot}	total power dissipation	$T_{amb} \leq 25$ °C	[1]			
	PMEG3005EB			-	310	mW
	PMEG3005EL			-	250	mW
T_j	junction temperature			-	150	°C
T_{amb}	ambient temperature			–65	+150	°C
T_{stg}	storage temperature			–65	+150	°C

[1] Device mounted on an FR4 Printed-Circuit Board (PCB), single-sided copper, tin-plated and standard footprint.

6. Thermal characteristics

Table 7. Thermal characteristics

Symbol	Parameter	Conditions		Min	Typ	Max	Unit
$R_{th(j-a)}$	thermal resistance from junction to ambient	in free air	[1][2]				
	PMEG3005EB			-	-	400	K/W
	PMEG3005EL			-	-	500	K/W
$R_{th(j-sp)}$	thermal resistance from junction to solder point		[3]				
	PMEG3005EB			-	-	75	K/W

[1] For Schottky barrier diodes thermal runaway has to be considered, as in some applications the reverse power losses P_R are a significant part of the total power losses.

[2] Device mounted on an FR4 PCB, single-sided copper, tin-plated and standard footprint.

[3] Soldering point of cathode tab.

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7. Characteristics

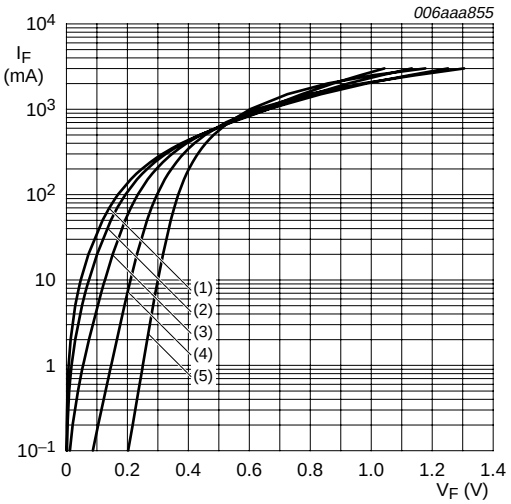
Table 8. Characteristics

T_{amb} = 25 °C unless otherwise specified.

Symbol	Parameter	Conditions		Min	Typ	Max	Unit
V_F	forward voltage		[1]				
		I_F = 0.1 mA		-	90	180	mV
		I_F = 1 mA		-	150	200	mV
		I_F = 10 mA		-	210	270	mV
		I_F = 100 mA		-	295	360	mV
		I_F = 500 mA		-	430	500	mV
I_R	reverse current	V_R = 10 V		-	15	200	µA
		V_R = 30 V		-	70	500	µA
C_d	diode capacitance	V_R = 1 V; f = 1 MHz		-	24	30	pF

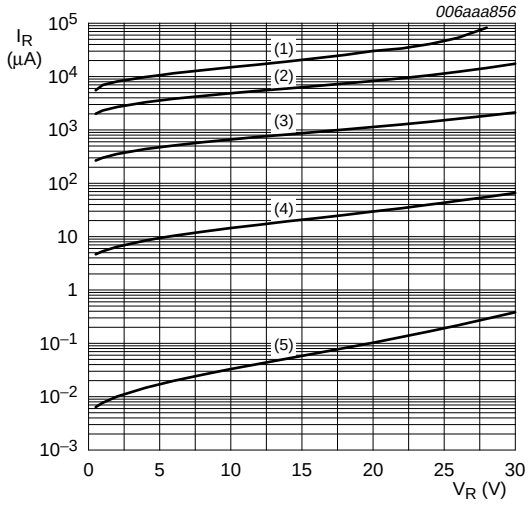
[1] Pulse test: $t_p \leq 300$ µs; $\delta \leq 0.02$.

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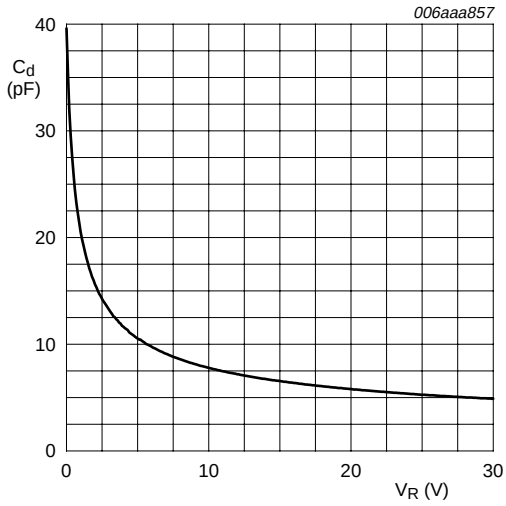
(1) T_{amb} = 150 °C
(2) T_{amb} = 125 °C
(3) T_{amb} = 85 °C
(4) T_{amb} = 25 °C
(5) T_{amb} = –40 °C

Fig 1. Forward current as a function of forward voltage; typical values



(1) T_{amb} = 150 °C
(2) T_{amb} = 125 °C
(3) T_{amb} = 85 °C
(4) T_{amb} = 25 °C
(5) T_{amb} = –40 °C

Fig 2. Reverse current as a function of reverse voltage; typical values



f = 1 MHz; T_{amb} = 25 °C

Fig 3. Diode capacitance as a function of reverse voltage; typical values

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8. Test information

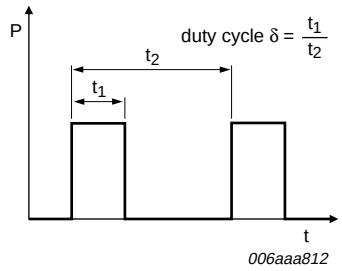


Fig 4. Duty cycle definition

9. Package outline

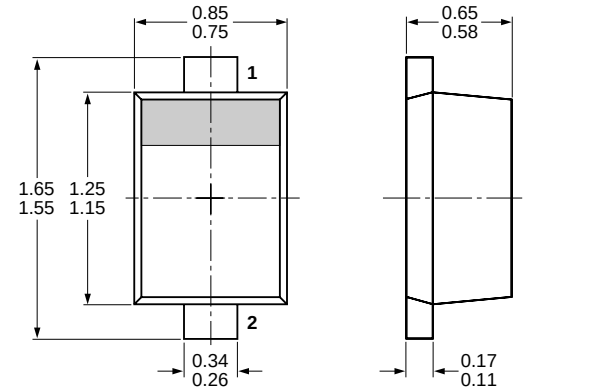


Fig 5. Package outline SOD523 (SC-79)

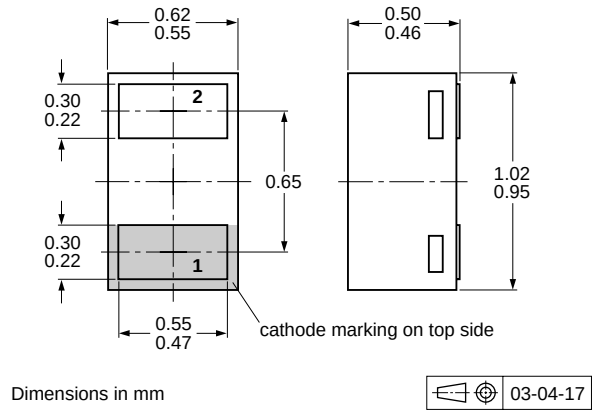


Fig 6. Package outline SOD882

10. Packing information

Table 9. Packing methods

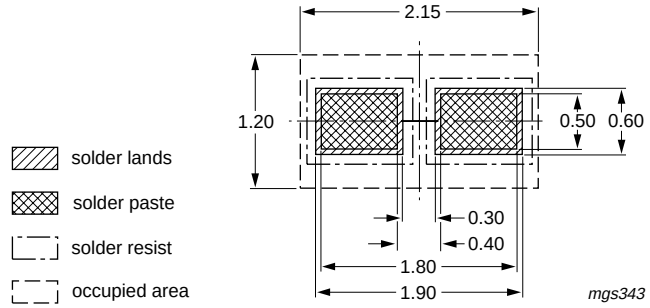
The indicated -xxx are the last three digits of the 12NC ordering code.[1]

Type number	Package	Description	Packing quantity		
			3000	8000	10000
PMEG3005EB	SOD523	2 mm pitch, 8 mm tape and reel	-	-315	-
		4 mm pitch, 8 mm tape and reel	-115	-	-135
PMEG3005EL	SOD882	2 mm pitch, 8 mm tape and reel	-	-	-315

[1] For further information and the availability of packing methods, see Section 14.

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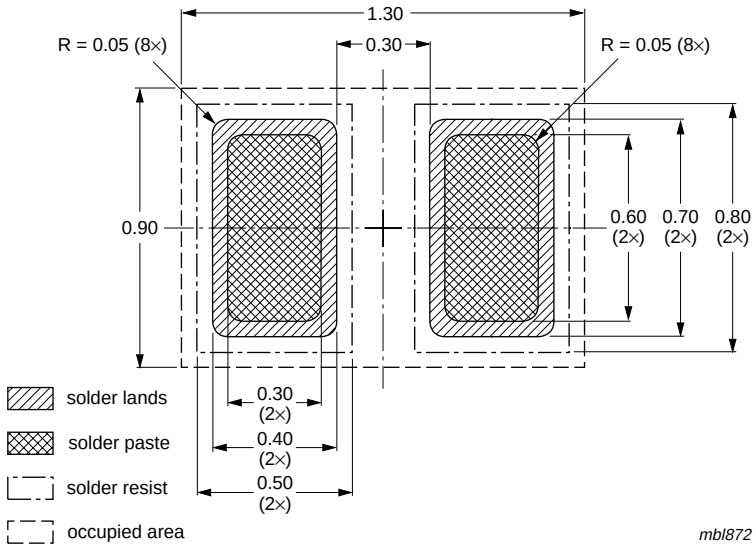
11. Soldering



Reflow soldering is the only recommended soldering method.

Dimensions in mm

Fig 7. Reflow soldering footprint SOD523 (SC-79)



Reflow soldering is the only recommended soldering method.

Dimensions in mm

Fig 8. Reflow soldering footprint SOD882

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12. Revision history

Table 10. Revision history

Document ID	Release date	Data sheet status	Change notice	Supersedes
PMEG3005EB_PMEG3005EL_1	20061129	Product data sheet	-	-

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13. Legal information

13.1 Data sheet status

Document status[1][2]	Product status[3]	Definition
Objective [short] data sheet	Development	This document contains data from the objective specification for product development.
Preliminary [short] data sheet	Qualification	This document contains data from the preliminary specification.
Product [short] data sheet	Production	This document contains the product specification.

[1] Please consult the most recently issued document before initiating or completing a design.

[2] The term 'short data sheet' is explained in section "Definitions".

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